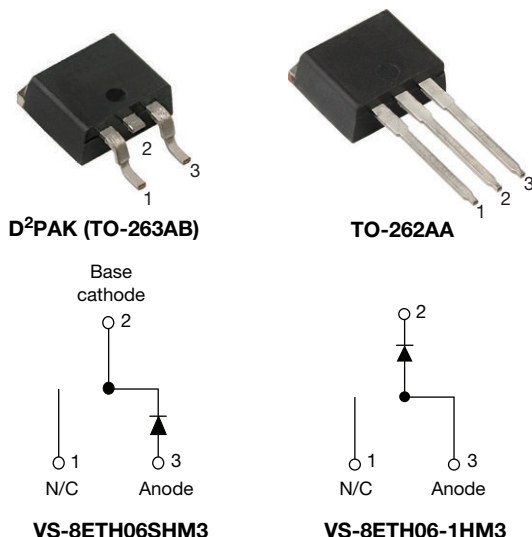


Hyperfast Rectifier, 8 A FRED Pt®



RoHS
COMPLIANT
HALOGEN
FREE

FEATURES

- Hyperfast recovery time
- Low forward voltage drop
- Low leakage current
- 175 °C operating junction temperature
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified, meets JESD 201, class 1 whisker test
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

MECHANICAL DATA

Case: D²PAK (TO-263AB), TO-262AA

Molding compound meets UL 94 V-0 flammability rating

Terminals: matte tin plated leads, solderable per J-STD-002

LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	8 A
V_R	600 V
V_F at I_F	1.3 V
t_{rr} typ.	18 ns
T_J max.	175 °C
Package	D ² PAK (TO-263AB), TO-262AA
Circuit configuration	Single

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Peak repetitive reverse voltage	V_{RRM}		600	V
Average rectified forward current	$I_{F(AV)}$	$T_C = 144$ °C	8	A
Non-repetitive peak surge current	I_{FSM}	$T_J = 25$ °C	90	
Peak repetitive forward current	I_{FM}		16	
Operating junction and storage temperatures	T_J, T_{Stg}		-55 to +175	°C

ELECTRICAL SPECIFICATIONS ($T_J = 25$ °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	$I_R = 100$ μ A	600	-	-	V
Forward voltage	V_F	$I_F = 8$ A	-	2.0	2.4	
		$I_F = 8$ A, $T_J = 150$ °C	-	1.3	1.8	
Reverse leakage current	I_R	$V_R = V_R$ rated	-	0.03	50	μ A
		$T_J = 150$ °C, $V_R = V_R$ rated	-	55	500	
Junction capacitance	C_T	$V_R = 600$ V	-	17	-	pF
Series inductance	L_S	Measured lead to lead 5 mm from package body	-	8.0	-	nH



DYNAMIC RECOVERY CHARACTERISTICS ($T_C = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t_{rr}	$I_F = 1\text{ A}$, $di_F/dt = 100\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$	-	18	22	ns
		$I_F = 8\text{ A}$, $di_F/dt = 100\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$	-	20	-	
		$T_J = 25\text{ }^{\circ}\text{C}$	-	25	-	
		$T_J = 125\text{ }^{\circ}\text{C}$	-	40	-	
Peak recovery current	I_{RRM}	$T_J = 25\text{ }^{\circ}\text{C}$	-	2.4	-	A
		$T_J = 125\text{ }^{\circ}\text{C}$	-	4.8	-	
Reverse recovery charge	Q_{rr}	$T_J = 25\text{ }^{\circ}\text{C}$	-	25	-	nC
		$T_J = 125\text{ }^{\circ}\text{C}$	-	120	-	
Reverse recovery time	t_{rr}	$I_F = 8\text{ A}$ $di_F/dt = 600\text{ A}/\mu\text{s}$ $V_R = 390\text{ V}$	-	33	-	ns
Peak recovery current	I_{RRM}		-	12	-	A
Reverse recovery charge	Q_{rr}		-	220	-	nC

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		-65	-	175	$^{\circ}\text{C}$
Thermal resistance, junction to case per leg	R_{thJC}		-	1.4	2	$^{\circ}\text{C}/\text{W}$
Thermal resistance, junction to ambient per leg	R_{thJA}	Typical socket mount	-	-	70	
Thermal resistance, case to heatsink	R_{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style D ² PAK (TO-263AB)	8ETH06SH			
		Case style TO-262AA	8ETH06-1H			

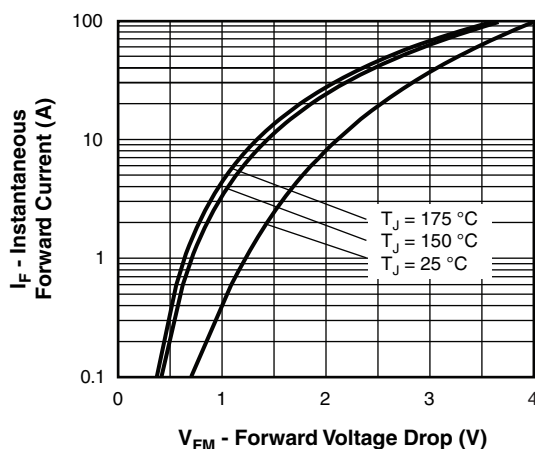


Fig. 1 - Maximum Forward Voltage Drop Characteristics

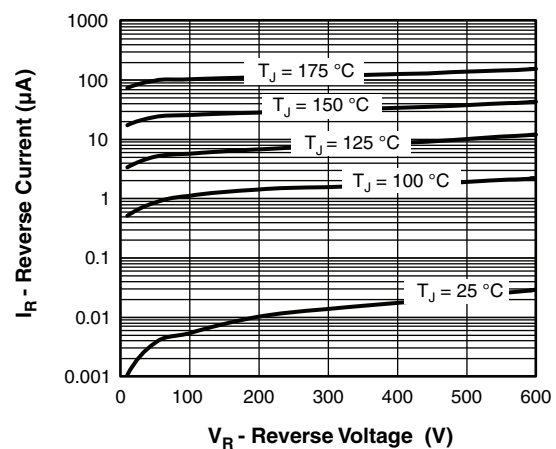


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

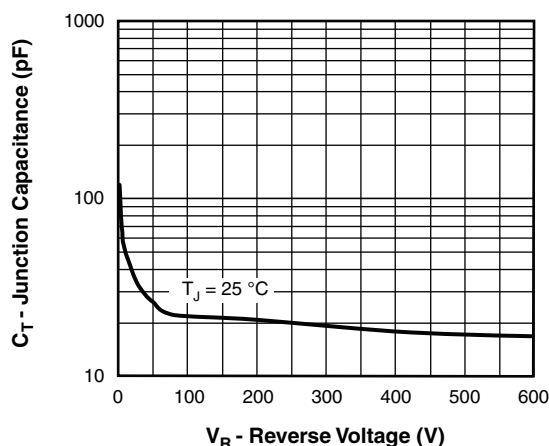


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

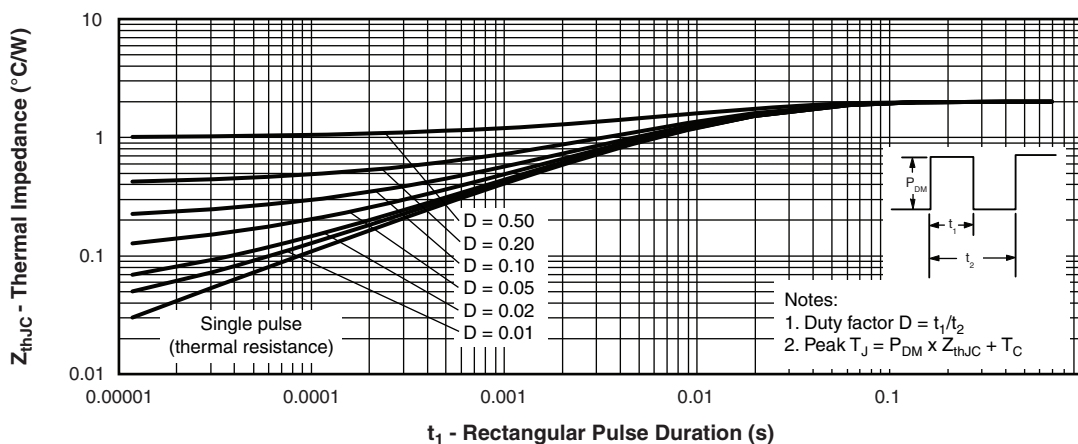
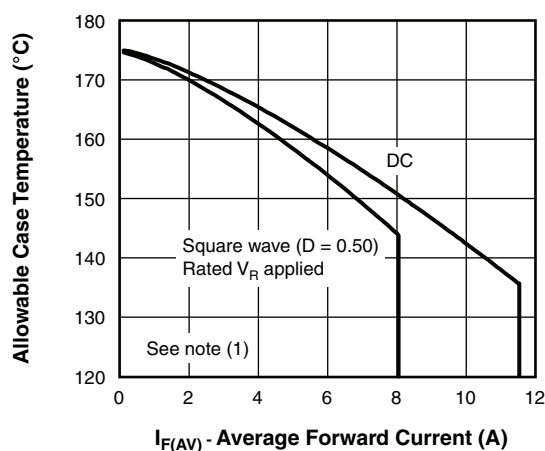

Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

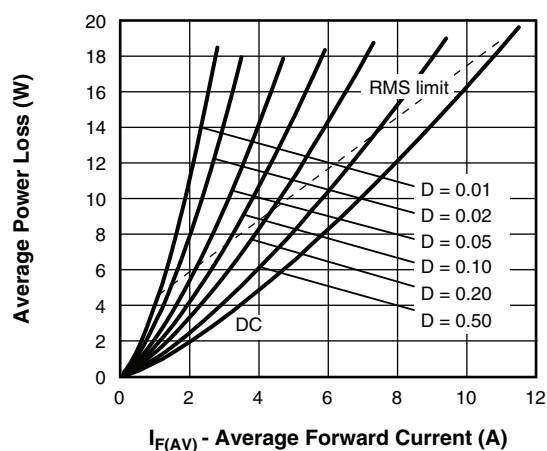


Fig. 6 - Forward Power Loss Characteristics

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$;
 P_d = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
 P_{dREV} = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = rated V_R

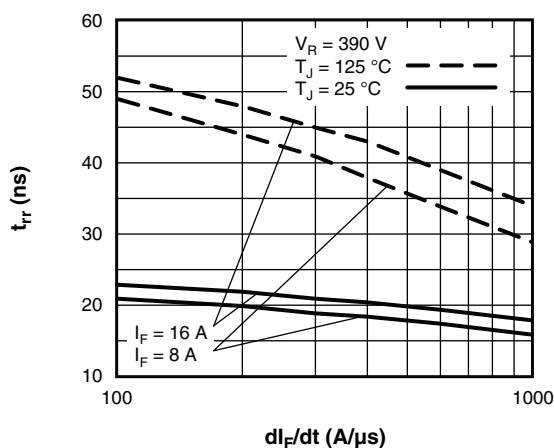
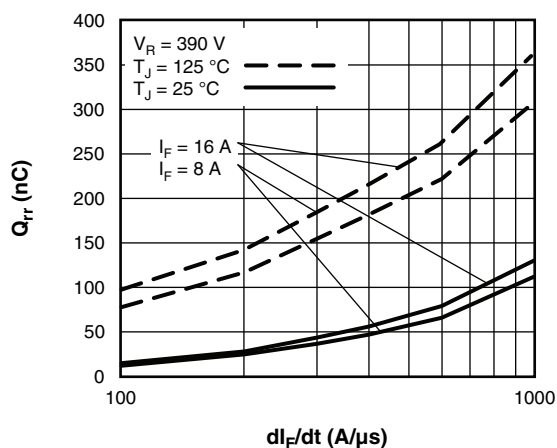
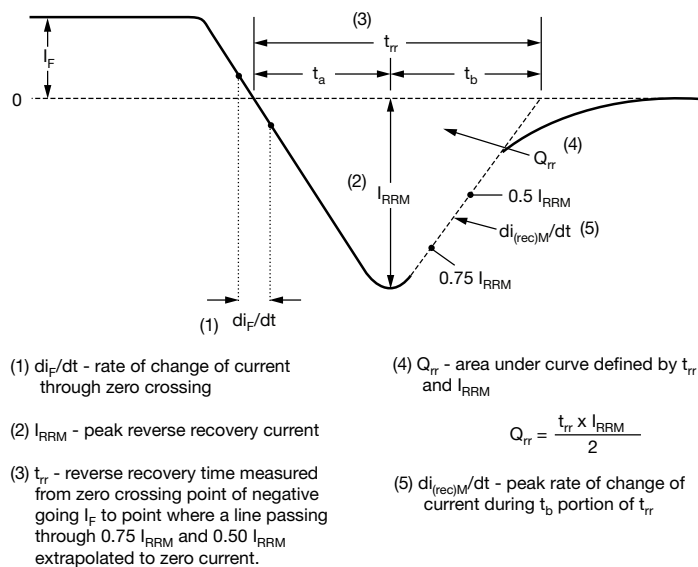

Fig. 7 - Typical Reverse Recovery Time vs. di_F/dt

Fig. 8 - Typical Stored Charge vs. di_F/dt


Fig. 9 - Reverse Recovery Waveform and Definitions

**ORDERING INFORMATION TABLE**

Device code	VS-	8	E	T	H	06	S	TRL	H	M3
	1	2	3	4	5	6	7	8	9	10

- | | | |
|-----------|---|--|
| 1 | - | Vishay Semiconductors product |
| 2 | - | Current rating (8 A) |
| 3 | - | E = single diode |
| 4 | - | T = TO-220, D ² PAK (TO-263AB) |
| 5 | - | H = hyperfast rectifier |
| 6 | - | Voltage rating (06 = 600 V) |
| 7 | - | • S = D ² PAK (TO-263AB)
• -1 = TO-262 |
| 8 | - | • None = tube (50 pieces)
• TRL = tape and reel (left oriented, for D ² PAK package)
• TRR = tape and reel (right oriented, for D ² PAK package) |
| 9 | - | H = AEC-Q101 qualified |
| 10 | - | M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free |

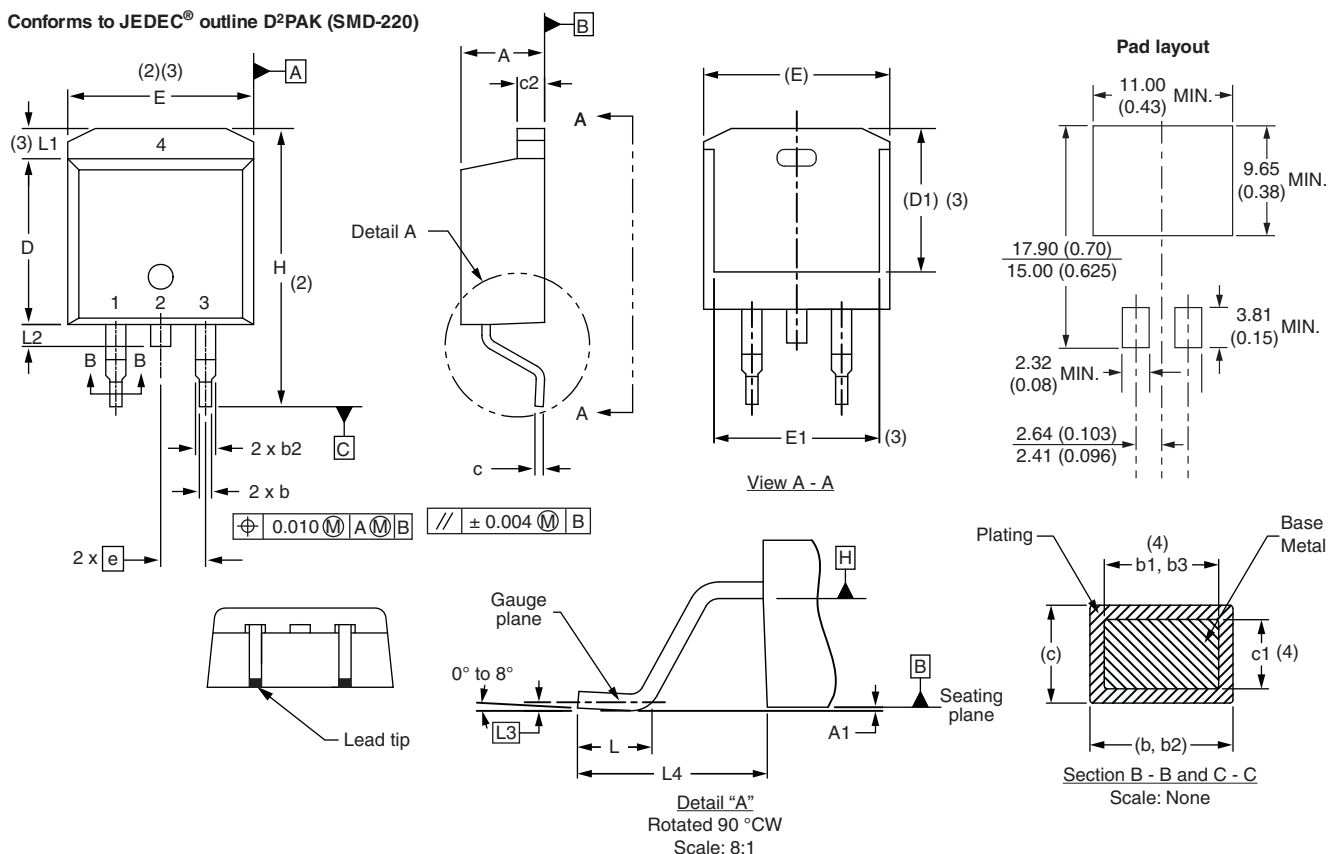
ORDERING INFORMATION (Example)		
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-8ETH06SHM3	50	Antistatic plastic tube
VS-8ETH06STRRHM3	800	13" diameter reel
VS-8ETH06STRLHM3	800	13" diameter plastic reel
VS-8ETH06-1HM3	50	Antistatic plastic tube

LINKS TO RELATED DOCUMENTS		
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?95046
	TO-262AA	www.vishay.com/doc?95419
Part marking information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444
	TO-262AA	www.vishay.com/doc?95443
Packaging information	D ² PAK (TO-263AB)	www.vishay.com/doc?95032

D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES		SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.				MIN.	MAX.			
A	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			E	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		e	2.54 BSC		0.100 BSC		
b2	1.14	1.78	0.045	0.070			H	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
c	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25 BSC		0.010 BSC		
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

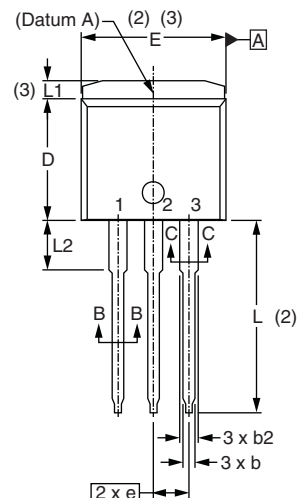
Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TQ-263AB

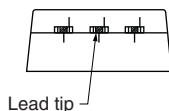
TO-262

DIMENSIONS in millimeters and inches

Modified JEDEC® outline TO-262

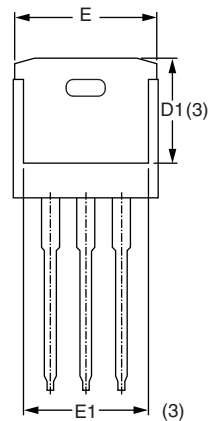
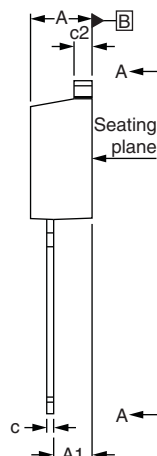


$\Phi 0.010 \text{ MAM} \text{ B}$

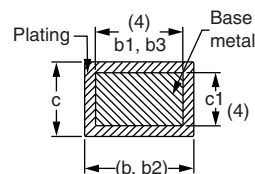


Lead assignments

- Diodes**
 1. - Anode (two die)/open (one die)
 2., 4. - Cathode
 3. - Anode



Section A - A



Section B - B and C - C
 Scale: None

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.36	3.71	0.132	0.146	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline



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